ABSTRACT

INTEGRATED CIRCUIT PACKAGING SYSTEM WITH PAD CONNECTION AND METHOD OF MANUFACTURE THEREOF

A method of manufacture of an integrated circuit packaging system includes: forming a lead having a horizontal ridge at a lead top side; forming a connection layer having an inner pad and an outer pad directly on the lead top side, the inner pad having an inner pad bottom surface; mounting an integrated circuit over the inner pad; applying a molding compound, having a molding bottom surface, over the integrated circuit, the inner pad, and the outer pad; and applying a dielectric directly on the molding bottom surface and the inner pad bottom surface.
(Fig. 1)